

AP1686

### **General Description**

The AP1686 is a high performance AC/DC power supply controller for LED lighting application. The device uses Pulse Frequency Modulation (PFM) method to build discontinuous conduction mode (DCM) flyback power supplies.

The AP1686 provides accurate constant voltage, constant current (CV/CC) regulation without requiring an opto-coupler and the secondary control circuitry. It also eliminates the need of loop compensation circuitry while maintaining good stability. The AP1686 can achieve excellent regulation and high average efficiency, yet meets no-load consumption less than 30mW.

It also has an adjustable built-in line compensation function to achieve tight CC.

The AP1686 is available in SOT-23-6 package.

#### **Features**

- Primary Side Control for Tight Constant Current and Constant Voltage
- 30mW No-load Input Power
- Bipolar Junction Transistor (BJT) Driving
- Open Circuit Protection
- Over Voltage Protection
- Short Circuit Protection
- SOT-23-6 Package

### **Applications**

LED Driver

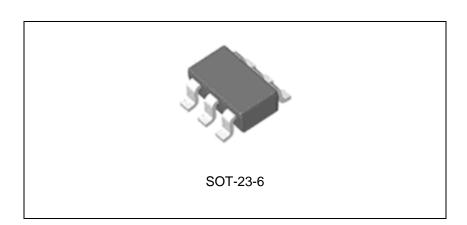


Figure 1. Package Type of AP1686



AP1686

# **Pin Configuration**

K6 Package (SOT-23-6)

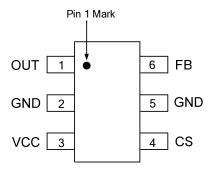


Figure 2. Pin Configuration of AP1686 (Top View)

# **Pin Description**

Pin Number	Pin Name	Function			
1	OUT	The OUT pin is used to turn on and turn off the power switch. When turning on the power switch, the OUT pin will output 30mA source current to support the base current of the power BJT. When turning off the power switch, the resistance between the OUT and GND will become to $5\Omega$			
2, 5	GND	The GND pin is the ground of the IC. When the power BJT is turned off, a fast reverse sinking current to the gate of BJT will flow out from this pin. Attention should be paid to in the PCB layout			
3	VCC	The VCC pin supplies the power for the IC. In order to get the correct operation of the IC, a capacitor with low ESR should be placed as close as possible to the VCC pin			
4	CS	The CS is the current sense pin of the IC. The IC will turn off the power BJT according to the voltage on the CS pin. When the power BJT is on, a current is output from the CS pin which is proportional to the line voltage to realize the function of line compensation			
6	FB	The CV and CC regulation are realized based on the voltage sampling of this pin			



AP1686

# **Functional Block Diagram**

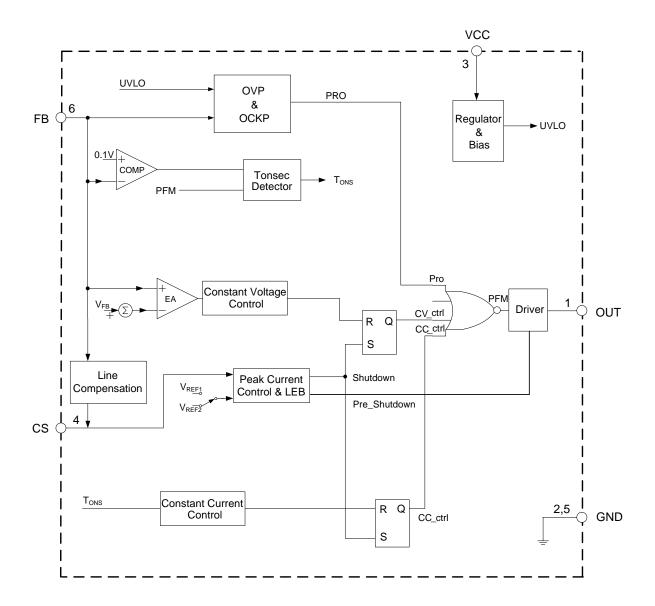
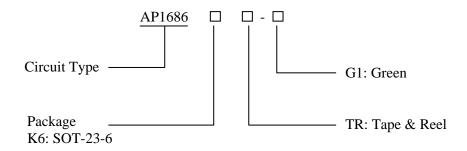


Figure 3. Functional Block Diagram of AP1686



**AP1686** 

### **Ordering Information**



Package	Temperature Range	Part Number	Marking ID	Packing Type	
SOT-23-6	-40 to 85°C	AP1686K6TR-G1	GBQ	Tape & Reel	

BCD Semiconductor's Pb-free products, as designated with "G1" suffix in the part number, are RoHS compliant and green.

# **Absolute Maximum Ratings (Note 1)**

Parameter	Symbol	Value	Unit	
Supply Voltage	$V_{CC}$	-0.3 to 30	V	
CS to GND Voltage		-0.3 to 7	V	
FB Input Voltage	$V_{FB}$	-40 to 7.5	V	
Source Current at OUT Pin	$I_{SOURCE}$	Internally Limited	A	
Operating Junction Temperature	$T_{\mathrm{J}}$	150	°C	
Storage Temperature	$T_{STG}$	-65 to 150	°C	
Lead Temperature (Soldering, 10 sec)	$T_{LEAD}$	300	°C	
Thermal Resistance (Junction to Ambient)	$\theta_{\mathrm{JA}}$	200	°C/W	
ESD (Human Body Model)		2000	V	

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.



AP1686

### **Electrical Characteristics**

 $V_{CC}$ =15V,  $T_A$ =25°C, unless otherwise specified.

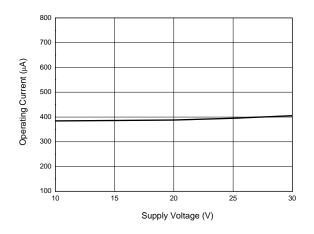
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
UVLO SECTION							
Startup Threshold		V <sub>TH</sub> (ST)		13	15.5	18	V
Minimal Operating Voltage		V <sub>OPR</sub> (MIN)		3	3.5	4.5	V
STANDBY CURR	STANDBY CURRENT SECTION						
Startup Current		$I_{ST}$	V <sub>CC</sub> =V <sub>TH</sub> (ST)-1V, Before startup	0	0.2	0.6	μA
Operating Current		$I_{CC}(OPR)$	Static current	250	400	600	
DRIVE OUTPUT SECTION							
Output Cumant	Sink	I <sub>SINK</sub>	Apply 1V @OUT pin	200	300	500	mA
Output Current	Source	I <sub>SOURCE</sub>		24	30	45	mA
CURRENT SENSE SECTION							
Current Sense Threshold Voltage		V <sub>CS</sub>		440	500	550	mV
Equivalent Current Sense Voltage Accuracy (Note 2)		$\frac{\Delta Vcs, eq}{Vcs, eq}$				4	%
Leading Edge Blanking		$t_{\rm LEB}$	The minimum power switch turn on time	300	475	720	ns
FEEDBACK INPUT SECTION							
Input Resistance of FB Pin		$R_{FB}$	V <sub>FB</sub> =4V	1	1.6	2	ΜΩ
Feedback Threshold		$V_{FB}$		3.7	3.974	4.21	V
LINE COMPENS	ATION SI	ECTION					
Line Com Transconductance (	pensation Note 2)	$g_{\mathrm{m}}$		1.14	1.43	1.72	μS
PROTECTION SECTION							
Over Voltage Protection		V <sub>FB</sub> (OVP)		6.5	7.5	8.5	V
Maximum On 7 Primary Side	Γime of	tonp (MAX)		11	18	50	μs

Note 2: The output current is given by  $I_{OUT} = \frac{Vcs, eq}{Rcs} \times \frac{Np}{Ns}$ 



AP1686

## **Typical Performance Characteristics**



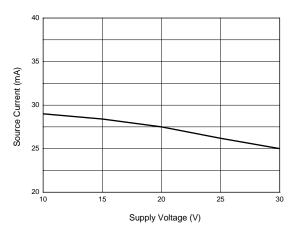
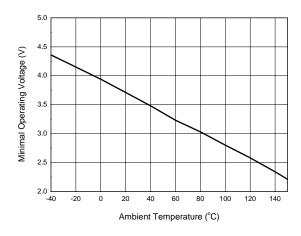
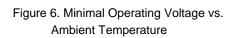


Figure 4. Operating Current vs. Supply Voltage

Figure 5. Source Current vs. Supply Voltage





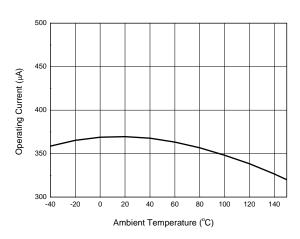
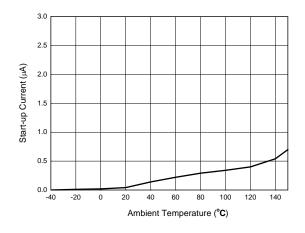


Figure 7. Operating Current vs. Ambient Temperature



AP1686

## **Typical Performance Characteristics (Continued)**



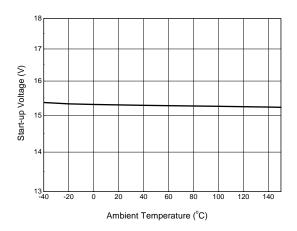


Figure 8. Start-up Current vs. Ambient Temperature

Figure 9. Start-up Voltage vs. Ambient Temperature

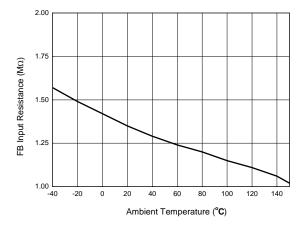


Figure 10. FB Input Resistance vs. Ambient Temperature

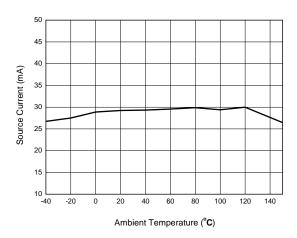


Figure 11. Source Current vs. Ambient Temperature



### **AP1686**

# **Typical Performance Characteristics (Continued)**

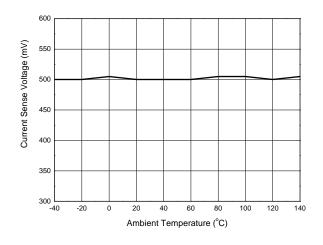


Figure 12. Current Sense Voltage vs.
Ambient Temperature

Figure 13. Primary Side Maximum On Time vs. Ambient Temperature

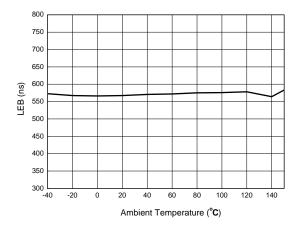


Figure 14. LEB vs. Ambient Temperature



**AP1686** 

# **Typical Application**

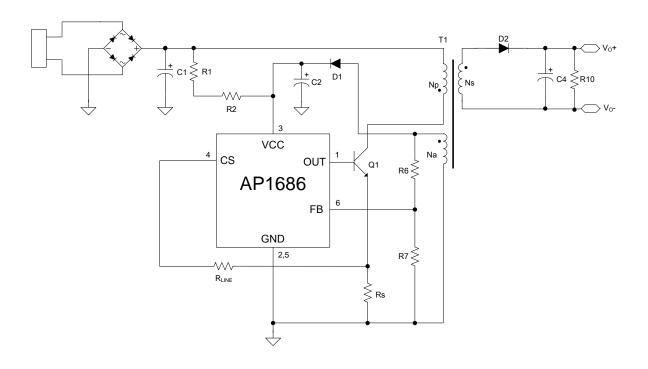


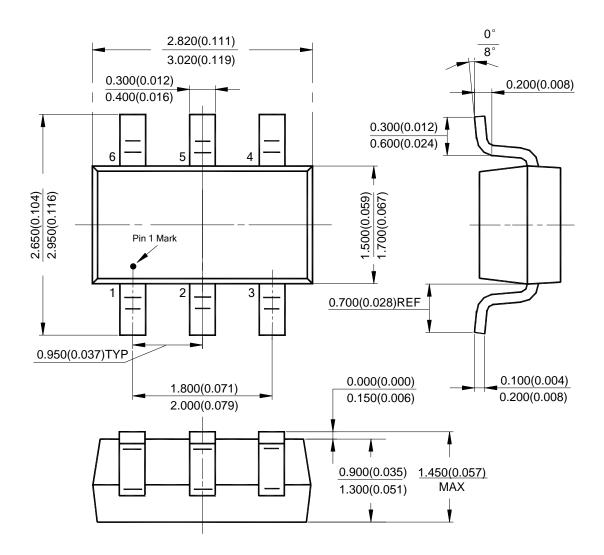
Figure 15. Typical LED Driver Application



AP1686

## **Mechanical Dimensions**

SOT-23-6 Unit: mm(inch)







#### **BCD Semiconductor Manufacturing Limited**

http://www.bcdsemi.com

#### IMPORTANT NOTICE

BCD Semiconductor Manufacturing Limited reserves the right to make changes without further notice to any products or specifications herein. BCD Semiconductor Manufacturing Limited does not assume any responsibility for use of any its products for any particular purpose, nor does BCD Semiconductor Manufacturing Limited assume any liability arising out of the application or use of any its products or circuits. BCD Semiconductor Manufacturing Limited does not convey any license under its patent rights or other rights nor the rights of others.

#### MAIN SITE

- Headquarters

BCD Semiconductor Manufacturing Limited

No. 1600, Zi Xing Road, Shanghai ZiZhu Science-based Industrial Park, 200241, China Tel: +86-21-24162266, Fax: +86-21-24162277

#### REGIONAL SALES OFFICE

Shenzhen Office

Shanghai SIM-BCD Semiconductor Manufacturing Co., Ltd., Shenzhen Office Unit A Room 1203, Skyworth Bldg., Gaoxin Ave.1.S., Nanshan District, Shenzhen,

China Tel: +86-755-8826 7951 Fax: +86-755-8826 7865

#### - Wafer Fab

Shanghai SIM-BCD Semiconductor Manufacturing Co., Ltd. 800 Yi Shan Road, Shanghai 200233, China Tel: +86-21-6485 1491, Fax: +86-21-5450 0008

#### **Taiwan Office**

BCD Semiconductor (Taiwan) Company Limited 4F, 298-1, Rui Guang Road, Nei-Hu District, Taipei,

Taiwan Tel: +886-2-2656 2808 Fax: +886-2-2656 2806

## USA Office BCD Semiconductor Corp. 30920 Huntwood Ave. Hayward, CA 94544, USA Tel: +1-510-324-2988 Fax: +1-510-324-2788